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IN THE CLAIMS

- 1. (Original) A binder composition comprising a mixture of a thermosetting spray dried phenolic resole resin and a crystalline phenolic compound having two or more hydroxyphenyl groups wherein the quantity of resole resin is from about 45% to 90% and the quantity of crystalline phenolic compound is 10% to 55%, by weight, of the binder.
- 2. (Original) The binder of claim 1 in the form of a blended powder.
- 3. (Original) The binder of claim 2 wherein the phenolic ingredient of the resole is phenol itself.
- 4. (Original) The binder of claim 2 wherein the resole resin is prepared with formaldehyde.
- 5. (Original) The binder of claim 2 wherein the resole resin is prepared with a molar ratio of 2 to 3 moles of formaldehyde for each mole of phenol.
- 6. (Original) The binder of claim 2 wherein the crystalline phenolic compound is bisphenol-A.
- 7. (Original) The binder of claim 2 wherein the crystalline phenolic compound is a member selected from the group consisting of bisphenol-A, bisphenol-AD, bisphenol-E, bisphenol-F, bisphenol-S, bisphenol Z, and mixtures thereof.
- 8. (Original) The binder composition of claim 2 wherein the crystalline compound is bisphenol-A, the quantity of resole resin is from about 60% to 80% and the quantity of the crystalline phenolic compound is 20% to 40% and wherein the resole is prepared from phenol itself and formaldehyde in a molar ratio of about 2 to 3 moles of formaldehyde for each mole of phenol.

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- (Original) A thermoset product prepared by heating a blend comprising a 9. thermosetting spray dried phenolic resole resin and a crystalline phenolic compound having two or more hydroxyphenyl groups wherein the quantity of resin is from about 45% to 90% and the quantity of crystalline phenolic compound is from about 10% to 55%, by weight, based on the weight of said resin and crystalline phenolic compound.
- (Original) The product of claim 9 wherein the crystalline phenolic compound is 10. bisphenol-A.
- (Original) The product of claim 9 wherein the blend comprises 55% to 85% of 11. resole resin and 15% to 45% of crystalline phenolic compound.
- (Original) The product of claim 9 wherein the blend comprises 60% to 80% of 12. the resole resin and 20% to 40% of the crystalline phenolic compound.
- (Original) A molding compound comprising: (a) a filler; and (b) a blend of a 13. crystalline phenolic compound having two or more hydroxyphenyl groups and a thermosetting spray dried phenolic resole resin wherein the quantity of resole varies from about 45% to 90% and the quantity of crystalline phenolic compound varies from about 55% to 10% based on the total weight of resole and crystalline phenolic compound.
- (Original) The molding compound of claim 13 which is substantially free of 14. hexamethylenetetramine.
- (Original) The molding compound of claim 13 wherein the quantity of the 15. blend varies from about 15% to 60% by weight of the molding compound.

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- (Original) A molded article comprising about 10% to 92% by weight of a filler 16. bound under heat and pressure with a blend of thermoset binder said binder comprising by weight, about 45% to 90% of a spray dried phenolic resole resin and about 10% to 55% of a crystalline phenolic compound having two or more hydroxyphenyl groups.
- (Original) The molded article of claim 16 wherein the crystalline phenolic 17. compound is bisphenol-A.
- (Original) A method for making a molded article which comprises subjecting a 18. mixture of a filler and a blend of thermosetting spray dried phenolic resole resin and a crystalline phenolic compound having two or more hydroxyphenyl groups to heat and pressure in order to cure the blend wherein the blend comprises from about 45% to 90%, by weight, of the resole and 10% to 55%, by weight, of the crystalline phenolic compound.
- (Original) The method of claim 18 wherein the crystalline phenolic compound 19. is bisphenol-A and the quantity of blend varies from about 8% to 90% by weight of the filler and blend
- (Currently Amended) The method of claim 18 wherein the molding temperature is... 20. from about 150°C to about 180°C.
- (Original) The method of claim 20 wherein the quantity of resole resin is from about 21. 60% to 80%, the quantity of crystalline phenolic compound is from 20% to 80% and the inmold cure time varies from about 45 to 180 seconds.
- (Original) A method for increasing the length of flow of a thermosetting spray-22. dried resole resin which comprises blending said resin with a crystalline phenolic compound having two or more hydroxyphenyl groups wherein the quantity, by weight, of resole resin to crystalline phenolic compound varies from about 45% to 90% for the resole resin and the quantity of crystalline compound varies from about 10% to 55%.

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(Original) The method of claim 22 wherein the quantity of resole resin varies from 23. about 60% to 80% and the quantity of crystalline compound varies from about 20% to 40%, by weight.